

RECEIVED
CENTRAL FAX CENTER

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Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

WHAT IS CLAIMED IS:

1. (Cancelled)
2. (Cancelled)
3. (Cancelled)
4. (Cancelled)
5. (Cancelled)
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23. (Cancelled)

24. (Cancelled)

25. (Cancelled)

26. (Cancelled)

27. (Cancelled)

28. (Cancelled)

29. (Cancelled)

30. (Cancelled)

31. (Previously Presented) A method for cleaning a substrate surface on a moving conveyor, comprising:

dry washing the substrate by introducing the substrate into a mixed atmosphere of an inert gas and water vapor under irradiation of ultraviolet light from a dielectric barrier discharge lamp;

decomposing organic substances deposited on the surface of the substrate with the dielectric barrier discharge lamp while splitting water vapor into a reducing active member $[H \cdot]$ and an oxidative active member $[\cdot OH]$, the active member $[H \cdot]$ and oxidative active member $[\cdot OH]$ react with the decomposed-organic substances to cause the decomposed organic substances to be removed from the surface of the substrate;

wet washing the substrate to remove inorganic contaminants by supplying washing water on the surface of the substrate; and

drying the substrate to eliminate washing water from the substrate surface.

32. (Currently Amended) A method for reducing a contact angle of a surface of a substrate in order to apply a liquid developer for the sake of etching, to form a circuit pattern uniformly on the entire surface of the substrate for applying a liquid developer on a substrate surface on a moving conveyor, comprising:

wet washing the substrate by supplying washing water to the surface of the substrate;

drying the substrate to eliminate washing water from the substrate surface;

placing the substrate in a dry washing stage under a mixed atmosphere of an inert gas and water to reduce the contact angle of the substrate surface, the inert gas and water vapor being under irradiation of ultraviolet light from a dielectric barrier discharge lamp to decompose organic substances deposited on a surface of the substrate while splitting water vapor into a reducing active member $[H \cdot]$ and an oxidative active member $[\cdot OH][[;]]$, whereby the reducing member $[H \cdot]$ and oxidative member $[\cdot OH]$ being subjected to the decomposed organic substances to cause a reaction with the decomposed organic substances,

subjecting the reducing and oxidative members $[H \cdot]$ and $[\cdot OH]$ to cause a reaction with the decomposed organic substances; and

convoying the substrate from the dry washing stage to a coating stage in order to coat the surface of the substrate having the reduced contact angle with the liquid developer.

~~coating the surface of the substrate with a liquid developer.~~